



Material Content Data Sheet



Sales Product Name	IPG20N06S4L-14A			Issued		29. August 2013		
MA#	MA001096388							
Package	PG-TDSON-8-10			Weight*		99.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.690	2.70	2.70	27039	27039
leadframe	non noble metal	iron	7439-89-6	0.046	0.05		467	
	inorganic material	phosphorus	7723-14-0	0.014	0.01		140	
	non noble metal	copper	7440-50-8	46.380	46.61	46.67	466176	466783
wire	non noble metal	aluminium	7429-90-5	0.723	0.73	0.73	7267	7267
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		891	
	plastics	epoxy resin	-	6.293	6.33		63251	
	inorganic material	silicondioxide	60676-86-0	37.935	38.13	44.55	381290	445432
leadfinish	non noble metal	tin	7440-31-5	1.396	1.40	1.40	14036	14036
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		14	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6062	6076
solder	non noble metal	tin	7440-31-5	0.066	0.07		667	
	noble metal	silver	7440-22-4	0.083	0.08		834	
	non noble metal	lead	7439-92-1	3.170	3.19	3.34	31866	33367
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

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